



Product Change Notification

Change Notification #: PCN114063-00
Change Title: All Tray Packed Component Products packed in full shipping and half height intermediate boxes, PCN114063-00, Transport Media, Full and half cushion fabricated Polyethylene packaging solution change

Date of Publication: November 16, 2015

Key Characteristics of the Change:

Transport Media





Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	January 4, 2016
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Description of Change to the Customer:

To align with keeping our materials environmentally friendly, Intel has chosen a new packing material.

All Intel tray component product families packed in full shipping and half height intermediate boxes will be changing from the molded Arcel cushions to a fabricated Polyethylene (PE) cushion. The cushion protection thickness remains the same as the current Arcel cushions. Intermediate and shipper boxes do not change. Please see the pictures below:

Current	New
<p align="center">Arcel</p>	<p align="center">Fabricated Polyethylene (PE)</p>
<p align="center">42g each, 1 set per shipping box</p>	<p align="center">71g each, 1 set per shipping box</p>
<p>Current full shipping box cushion</p>	<p>New full shipping box cushion</p>
	
<p>Current half shipping box cushion</p>	<p>New half shipping box cushion</p>
	

Customer Impact of Change and Recommended Action:

Customers may see both molded Arcel and fabricated Polyethylene (PE) cushions in full and half size packaging solutions until inventories in the Arcel cushions have been depleted.

Customers may want to notify their shipping and receiving departments of this change.

Products Affected / Intel Ordering Codes:

All tray packed component products that use the full and half height intermediate boxes are affected by this change.

PCN Revision History:

Date of Revision:
November 16, 2015

Revision Number:
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Reason:
Originally Published PCN



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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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